

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Tai-Chong CHAI *et al.*

Serial No.: 09/497,421

Filed: February 2, 2000



Date: December 3, 2001

Group Art Unit: 2815

Examiner: L. Cruz

#14/B
98
12/1/01

For: LEAD FRAME FOR AN INTEGRATED CIRCUIT CHIP (SMALL WINDOW)Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

AMENDMENT**35 U.S.C. §132; 37 C.F.R. §1.111**

This is responsive to the Office Action, reciting a July 3, 2001 mailing date, regarding the above-identified Application, in view of a November 5, 2001 telephone interview. Please reconsider allowability of the Application amended as follows:

IN THE CLAIMS

Please amend claims 1, 12 and 13 as follows:

1. (Twice Amended) A lead frame, for an integrated circuit chip having a frame engaging bottom surface, comprising a plurality of unitary sidebars, each of said sidebars having an inner side and an outer side, said inner sides defining a central aperture, said outer sides defining a chip-support zone, said zone being smaller in each dimension than a corresponding dimension of the chip, each sidebar having an upper chip-supporting surface for engaging the bottom surface of the chip.

12. (Amended) A lead frame for connecting and supporting an integrated circuit chip having an outer chip edge, comprising frame including interconnected unitary side bars defining a central aperture and an outer frame edge, said frame edge being disposed within the outer chip edge, thus having no shoulder, and therefore minimizing fillet formation, and haven a contact surface for securing the chip thereto.